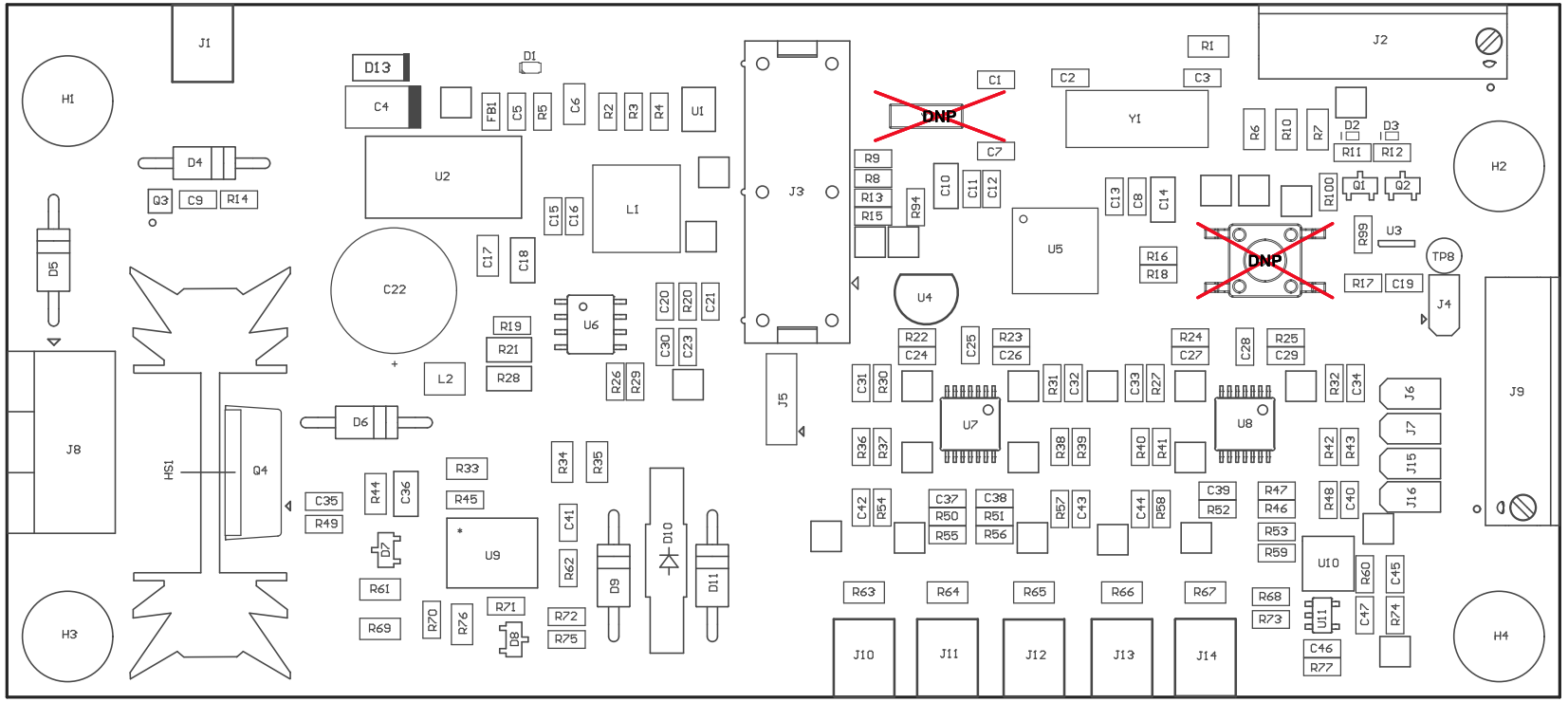
ZZ2 Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

ZZ1 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

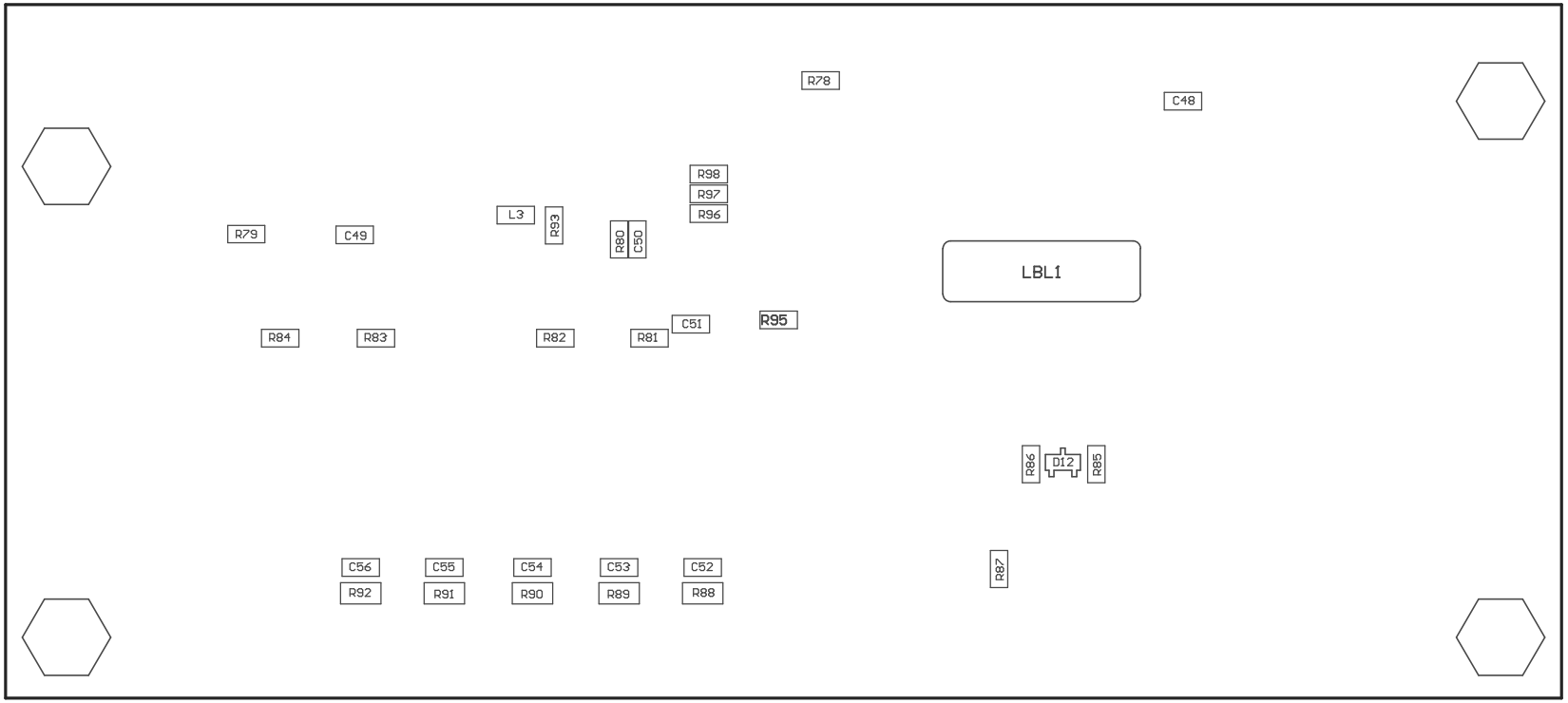
ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00498	REV: E2	Not In VersionControl
IGNORE -> ASSEMBLY TOP			
PLOT NAME = Top Assembly Drawing	GENERATED : 6/2/2015 2:44:59 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00498	REV: E2	SVN REV: Not In VersionControl
	IGNORE -> ASSEMBLY BOTTOM		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 6/2/2015 2:44:59 PM		TEXAS INSTRUMENTS

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